## INTEGRATED CIRCUITS

## DATA SHEET

# SA5224 FDDI fiber optic postamplifier

Product specification
Replaces datasheet NE/SA5224 of 1995 Apr 26
IC19 Data Handbook

1998 Oct 07





## FDDI fiber optic postamplifier

**SA5224** 

#### **DESCRIPTION**

The SA5224 is a high-gain limiting amplifier that is designed to process signals from fiber optic preamplifiers. Capable of operating at 125Mb/s, the chip is FDDI compatible and has input signal level-detection with a user-adjustable threshold. The DATA and LEVEL-DETECT outputs are differential for optimum noise margin and ease of use. Also available is the SA5225 which is an ECL 10K version of the SA5224.

#### **FEATURES**

- Wideband operation: 1.0kHz to 120MHz typical
- Applicable in 155Mb/s OC3/SONET receivers
- Operation with single +5V or -5.2V supply
- Differential 100k ECL outputs
- Programmable input signal level-detection
- Fully differential for excellent PSRR to 1GHz

#### **PIN DESCRIPTION**

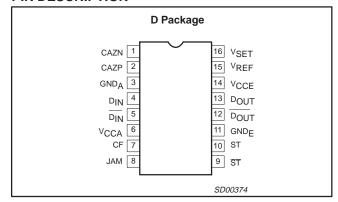


Figure 1. Pin Configuration

### **APPLICATIONS**

- FDDI
- Data communication in noisy industrial environments
- LANs

## ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
16-Pin Plastic Small Outline (SO) package	−40 to +85°C	SA5224D	SOT109-1

#### **BLOCK DIAGRAM**

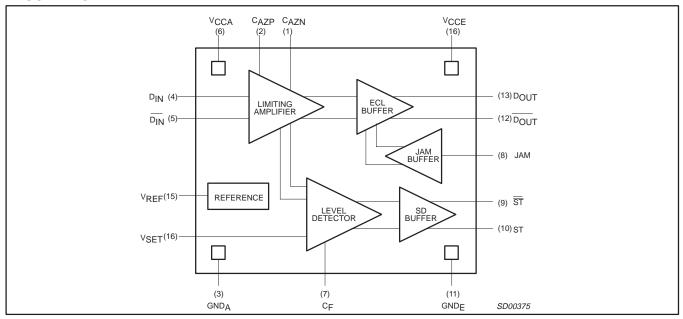


Figure 2. Block Diagram

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## **PIN DESCRIPTIONS**

PIN NO.	NAME	FUNCTION
1	C <sub>AZN</sub>	Auto-zero capacitor pin. Connecting a capacitor between this pin and C <sub>AZP</sub> will cancel the offset voltage of the limiting amplifier.
2	C <sub>AZP</sub>	Auto-zero capacitor pin. Connecting a capacitor between this pin and C <sub>AZN</sub> will cancel the offset voltage of the limiting amplifier.
3	GND <sub>A</sub>	Analog GND pin. Connect to ground for +5V upshifted ECL operation. Connect to -5.2V for standard ECL operation. Must be at same potential as GND <sub>E</sub> (Pin 11).
4	D <sub>IN</sub>	Differential input. DC bias level is set internally at approximately 2.9V. Complimentary to $\overline{D_{IN}}$ (Pin 5).
5	D <sub>IN</sub>	Differential input. DC bias level is set internally at approximately 2.9V. Complimentary to D <sub>IN</sub> (Pin 4).
6	V <sub>CCA</sub>	Analog power supply pin. Connect to a +5V supply for upshifted ECL operation. Connect to ground for standard ECL operation. Must be at same potential as V <sub>CCE</sub> (Pin 14).
7	C <sub>F</sub>	Filter capacitor for level detector. Capacitor should be connected between this pin and V <sub>CCA</sub> .
8	JAM	This ECL-compatible input controls the output buffers $\overline{D_{OUT}}$ and $D_{OUT}$ (Pins 12 and 13). When an ECL LOW signal is applied, the outputs will follow the input signal. When an ECL HIGH signal is applied, the $D_{OUT}$ and $\overline{D}_{OUT}$ pins will latch into LOW and HIGH states, respectively. When left unconnected, this pin is actively pulled-low (JAM OFF).
9	ST	Input signal level-detect STATUS. This ECL output is high when the input signal is below the user programmable threshold level.
10	ST	ECL compliment of ST (Pin 9).
11	GND <sub>E</sub>	Digital GND pin. Connect to ground for +5V upshifted ECL operation. Connect to a negative supply for normal ECL operation. Must be at the same potential as GND <sub>A</sub> (Pin 3).
12	D <sub>OUT</sub>	ECL-compatible output. Nominal level is V <sub>CCE</sub> -1.3V. When JAM is HIGH, this pin will be forced into an ECL HIGH condition. Complimentary to D <sub>OUT</sub> (Pin 13).
13	D <sub>OUT</sub>	ECL-compatible output. Nominal level is V <sub>CCE</sub> -1.3V. When JAM is HIGH, this pin will be forced into an ECL LOW condition. Complimentary to $\overline{D_{OUT}}$ (Pin 12).
14	V <sub>CCE</sub>	Digital power supply pin. Connect to a +5V supply for upshifted ECL operation. Connect to ground during normal ECL operation. Must be at the same potential as V <sub>CCA</sub> (Pin 6).
15	$V_{REF}$	Reference voltage for threshold level voltage divider. Nominal value is approximately 2.64V.
16	$V_{SET}$	Input threshold level setting circuit. This input can come from a voltage divider between V <sub>REF</sub> and GND <sub>A</sub> .

## **ABSOLUTE MAXIMUM RATINGS**

SYMBOL	PARAMETER	RATING	UNITS
V <sub>CC</sub>	Power supply (V <sub>CC</sub> - GND)	6	V
T <sub>A</sub>	Operating ambient	-45 to +85	°C
TJ	Operating junction	-55 to +150	°C
T <sub>STG</sub>	Storage	-65 to +150	°C
P <sub>D</sub>	Power dissipation, T <sub>A</sub> = 25°C (still air) <sup>1</sup> 16-pin Plastic SO	1100	mW

## NOTE:

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	RATING	UNITS
V <sub>CC</sub>	Supply voltage	4.5 to 5.5	V
T <sub>A</sub>	Ambient temperature ranges	-40 to +85	°C
TJ	Junction temperature ranges	-40 to +110	°C

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<sup>1.</sup> Maximum dissipation is determined by the ambient temperature and the thermal resistance,  $\theta_{JA}$ : 16-pin SO:  $\theta_{JA}$  = 110°C/W

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#### DC ELECTRICAL CHARACTERISTICS

Min and Max limits apply over operating temperature at  $V_{CC}$  = 5V  $\pm 10\%$ , unless otherwise specified. Typical data apply at  $T_A$  = 25 $^{\circ}C$  and  $V_{CC}$  =

OVMDOL	DADAMETED	TEGT COMPITIONS		SA5224		
SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT
V <sub>IN</sub>	Input signal voltage single-ended differential		.002 .004		1.5 3.0	V <sub>P-P</sub>
Vos	Input offset voltage <sup>2</sup>				50	μV
V <sub>N</sub>	Input RMS noise <sup>2</sup>				60	μV
$V_{TH}$	Input level-detect programmability single-ended	V <sub>IN</sub> = 200kHz square wave	2		12	mV <sub>P-P</sub>
V <sub>HYS</sub>	Level-detect hysteresis		4	5	6	dB
Icc	V <sub>CCA</sub> + V <sub>CCE</sub> supply current	No ECL loading		27	35	mA
I <sub>INL</sub>	JAM input current	Pin 8 = 0V	-10		10	μΑ
V <sub>OHMAX</sub>	Maximum logic high <sup>1</sup>				-0.880	$V_{DC}$
V <sub>OHMIN</sub>	Minimum logic high <sup>1</sup>		-1.055			V <sub>DC</sub>
V <sub>OLMAX</sub>	Maximum logic low <sup>1</sup>				-1.620	V <sub>DC</sub>
V <sub>OLMIN</sub>	Minimum logic low <sup>1</sup>		-1.870		1	V <sub>DC</sub>
V <sub>IH</sub>	Minimum input for JAM = high <sup>1</sup>		-1.165			V <sub>DC</sub>
V <sub>IL</sub>	Maximum input for JAM = low1				-1.490	$V_{DC}$

#### NOTES:

## **AC ELECTRICAL CHARACTERISTICS**

Typical data apply at T\_A = 25 °C and V\_CC = +5V. Min and Max limits apply for 4.5  $\leq$  V\_CC  $\leq$  5.5V.

SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT
BW <sub>1</sub>	Lower –3dB bandwidth	$C_{AZ} = 0.1 \mu F$	0.5	1.0	1.5	kHz
BW <sub>2</sub>	Upper –3dB bandwidth		90	120	150	MHz
R <sub>IN</sub>	Input resistance	Pin 4 or 5	2.9	4.5	7.6	kΩ
C <sub>IN</sub>	Input capacitance	Pin 4 or 5			2.5	pF
t <sub>r</sub> , t <sub>f</sub>	ECL output <sup>3</sup> risetime, falltime	$R_{L} = 50\Omega$ $To V_{CCE} - 2V$ $20-80\%$	1.2		2.2	ns
t <sub>PWD</sub>	Pulsewidth distortion				0.3	ns <sub>P-P</sub>
R <sub>AZ</sub>	Auto zero output resistance	Pin 1 or 2	155	250	423	kΩ
R <sub>F</sub>	Level-detect filter resistance	Pin 7	14	24	41	kΩ
t <sub>LD</sub>	Level-detect time constant	$C_F = 0$	0.5	1.0	2.0	μs

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<sup>1.</sup> These ECL specifications are referenced to the  $V_{CCE}$  rail and apply for  $T_A = 0^{\circ}C$  to  $85^{\circ}C$ . 2. Guaranteed by design.

<sup>1.</sup> Both outputs should be terminated identically to minimize differential feedback to the device inputs on a PC board or substrate.

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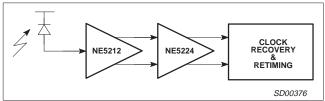


Figure 3. Typical Fiber Optic Receiving System

## **INPUT BIASING**

The DATA INPUT pins (4 and 5) are DC biased at approximately 2.9V by an internal reference generator. The SA5224 can be DC coupled, but the driving source must operate within the allowable 1.4V to 4.4V input signal range (for  $V_{CC}=5V$ ). If AC coupling is used to remove any DC compatibility requirement, the coupling capacitors C1 and C2 must be large enough to pass the lowest input frequency of interest. For example, .001µF coupling capacitors react with the internal 4.5k input bias resistors to yield a lower -3dB frequency of 35kHz. This then sets a limit on the maximum number of consecutive "1"s or "0"s that can be sensed accurately at the system data rate. Capacitor tolerance and resistor variation (2.9k to 7.6k) must be included for an accurate calculation.

### **AUTO-ZERO CIRCUIT**

Figure 5 also shows the essential details of the auto-zero circuit. A feedback amplifier (A4) is used to cancel the offset voltage of the forward signal path, so the input to the internal ECL comparator (A6) is at its toggle point in the absence of any input signal. The time constant of the cancelling circuitry is set by an external capacitor (CAZ) connected between Pins 1 and 2. The formula for the lower –3dB frequency is:

$$f_{-3dB} = \frac{150}{2\pi \cdot R_{AZ} \cdot C_{AZ}}$$

where  $R_{AZ}$  is the internal driving impedance which can vary from 155k to 423k over temperature and device fabrication limits. The input coupling time constant must also be considered in determining the lower frequency response of the SA5224.

## INPUT SIGNAL LEVEL-DETECTION

The SA5224 allows for user programmable input signal level-detection and can automatically disable the switching of its

ECL data outputs if the input is below a set threshold. This prevents the outputs from reacting to noise in the absence of a valid input signal, and insures that data will only be transmitted when the input signal-to-noise ratio is sufficient for low bit-error-rate system operation. Complimentary ECL flags (ST and STB) indicate whether the input signal is above or below the desired threshold level.

Figure 6 shows a simplified block diagram of the SA5224 level-detect system. The input signal is amplified and rectified before being compared to a programmable reference. A filter is included to prevent noise spikes from triggering the level-detector. This filter has a nominal 1µs time constant, and additional filtering can be achieved by using an external capacitor (CF) from Pin 7 to  $V_{CCA}$  (the internal driving impedance is nominally 24k). The resultant signal is then compared to a programmable level,  $V_{SET}$ , which is set by an internal voltage reference (2.64V) and an external resistor divider (R1 and R2). The value of R1 + R2 should be maintained at approximately 5k.

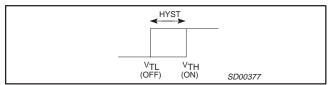


Figure 4.

The circuit is designed to operate accurately over a differential 2-12mV<sub>P-P</sub> square-wave input level detect range. This level,  $V_{\text{SET}}/100$ , is the average of  $V_{\text{TH}}$  and  $V_{\text{TL}}.$ 

Nominal hysteresis of 5dB is provided by the complimentary ECL

output comparator yielding  $V_{TL} = \frac{V_{SET}}{139}$  and  $V_{TH} = \frac{V_{SET}}{78}$ . For example, with  $V_{SET} = 1.2V$ , a 15.4m $V_{P-P}$  square-wave differential input will drive the ST pin high, and an input level below 8.6m $V_{P-P}$  will drive the ST pin low.

Since a "JAM" function is provided (Pin 8) and can force the data outputs to a predetermined state ( $D_{OUT} = LOW, \overline{D_{OUT}} = HIGH$ ), the  $\overline{ST}$  and JAM pins can be connected together to automatically disable signal transmission when the chip senses that the input signal is below the desired threshold. JAM (Pin 8) low enables the Data Outputs.  $\overline{ST}$  will be in a high ECL state for input signals below threshold.

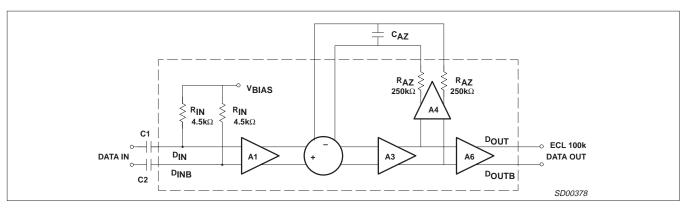


Figure 5. SA5224 Forward Gain Path Including Auto-Zero

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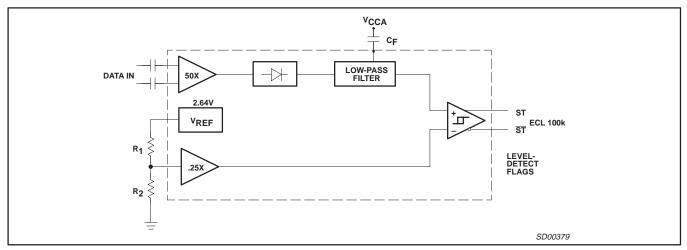


Figure 6. SA5224 Input Signal Level-Detect System

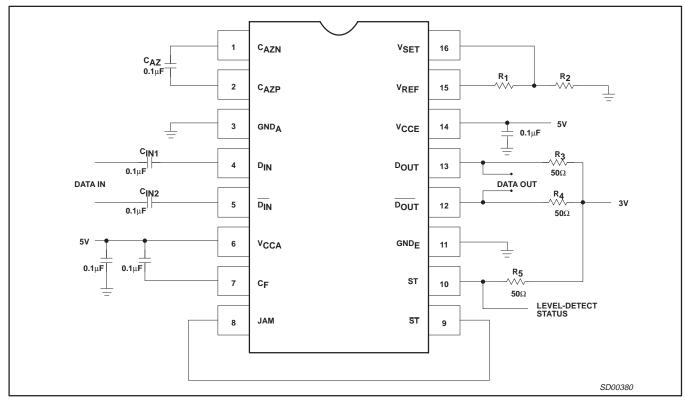


Figure 7. Application with  $V_{CC} = 5.0V$ 

NOTE: A  $50\Omega$  resistor is required from Pin 9 to 3V only if the  $\overline{ST}$  pin is required to meet 100k ECL specifications.

## **Die Sales Disclaimer**

Due to the limitations in testing high frequency and other parameters at the die level, and the fact that die electrical characteristics may shift after packaging, die electrical parameters are not specified and die are not guaranteed to meet electrical characteristics (including temperature range) as noted in this data sheet which is intended only to specify electrical characteristics for a packaged device.

All die are 100% functional with various parametrics tested at the wafer level, at room temperature only (25°C), and are guaranteed to be 100% functional as a result of electrical testing to the point of wafer sawing only. Although the most modern processes are utilized for wafer sawing and die pick and place into waffle pack carriers, it is impossible to guarantee 100% functionality through this process. There is no post waffle pack testing performed on individual die.

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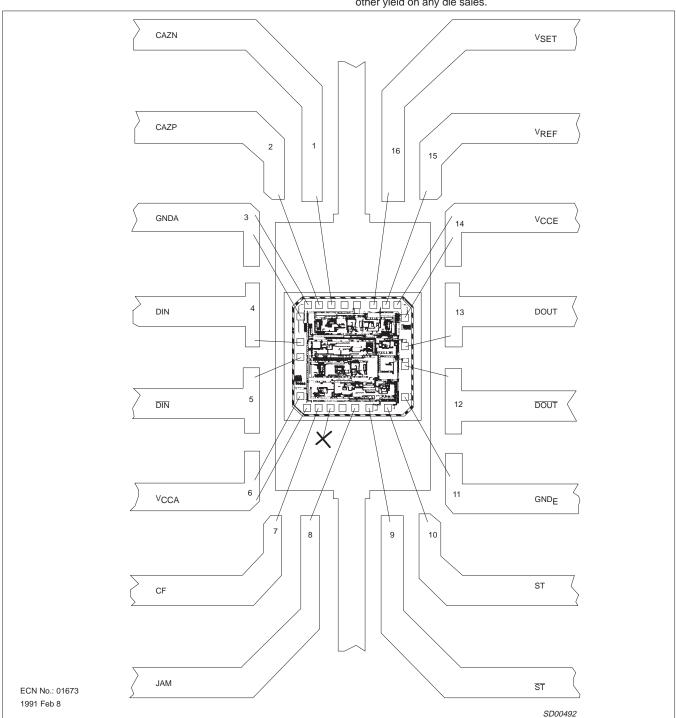


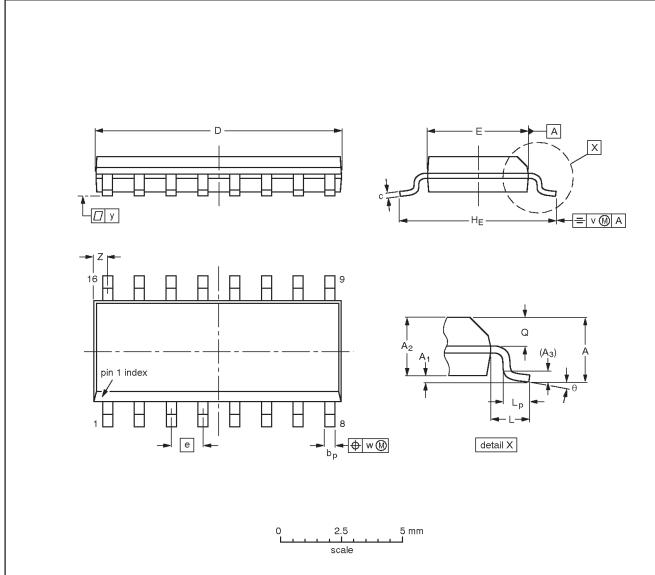
Figure 8. SA5224 Bonding Diagram

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## SO16: plastic small outline package; 16 leads; body width 3.9 mm

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## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	c	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT109-1	076E07S	MS-012AC				<del>95-01-23</del> 97-05-22

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## **NOTES**

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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